



Receipt

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

For: LEAD-FREE SOLDER PASTE FOR REFLOW SOLDERING

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

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Dear Sir:

An error has been noted on the Official Filing Receipt in the referenced application. Namely, the inventor Masato Shimamura has been listed twice. Please issue a Corrected Official Filing Receipt correcting this error as marked in red on the attached copy of the Official Filing Receipt.

Respectfully submitted,

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Date: Jan 10, 2001

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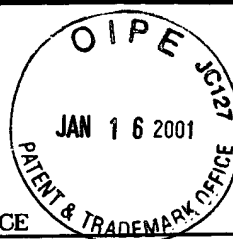
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Signature Michael Tobias  
Michael Tobias



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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/642,765	08/22/2000	1725	840	1023/HIROSE		12	1

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## FILING RECEIPT



\*OC000000005652857\*

Date Mailed: 01/04/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

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## Continuing Data as Claimed by Applicant

## Foreign Applications

If Required, Foreign Filing License Granted 10/11/2000

## Title

Lead-free solder paste for reflow soldering

## Preliminary Class

228

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Data entry by : MASON, JAMES

Team : OIPE

Date: 01/04/2001





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Bib Data Sheet

CONFIRMATION NO. 8065

<b>SERIAL NUMBER</b> 09/642,765	<b>FILING DATE</b> 08/22/2000 <b>RULE</b>	<b>CLASS</b> 228	<b>GROUP ART UNIT</b> 1725	<b>ATTORNEY DOCKET NO.</b> 1023/HIROSE
<b>APPLICANTS</b> Toshihiko Tauguchi, Kitakatsushika-gun, JAPAN; Satoru Akita, Sohka-shi, JAPAN; Masato Shimamura, Sohka-shi, JAPAN; Ryoichi Suzuki, Saratoga, CA; Tetsuya Okuno, San Jose, CA;				
<b>** CONTINUING DATA *****</b> <i>none 4</i>				
<b>** FOREIGN APPLICATIONS *****</b> <i>none 4</i>				
<b>IF REQUIRED, FOREIGN FILING LICENSE</b> <b>GRANTED ** 10/11/2000</b>				
Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance Verified and Acknowledged Examiner's Signature <i>CC</i> Initials	<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b>	<b>TOTAL CLAIMS</b> 12	<b>INDEPENDENT CLAIMS</b> 1
<b>ADDRESS</b> 27649				
<b>TITLE</b> Lead-free solder paste for reflow soldering				
<b>FILING FEE RECEIVED</b> 840	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	

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